



## Final Product Change Notification

201708036F01

**Issue Date:** 03-Sep-2017

**Effective Date:** 01-Dec-2017

Dear *Tracy Hoglin*,

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



# QUALITY

### Change Category

Wafer Fab Process

Wafer Fab Materials

Wafer Fab Location

Assembly Process

Assembly Materials

Assembly Location

Product Marking

Mechanical Specification

Packing/Shipping/Labeling

Test Location

Test Process

Test Equipment

Design

Errata

Electrical spec./Test coverage

MC3467x Family  
Assembly Site Transfer  
from CARSEM to  
ASECL

### Details of this Change

NXP Semiconductors announces the Assembly site transfer for the MC3467x devices associated with this notification, from the current CARSEM, Malaysia assembly site to the ASECL, Taiwan assembly site. The assembly site change is required due to CARSEM announced assembly site closure.

The assembly site transfer to ASECL results in the following BOM changes:

Mold Compound: Changed to Sumitomo G700LA, from Sumitomo G770HC

Die Attach: Changed to Hitachi EN4900, from Henkel QMI519

Lead Frame: Changed to Rough Ni PPF (NiPdAu) with exposed lead (E-type), from PPF (NiPdAu) with standard lead (S-type).

The lead frame change from standard lead (S-type) to exposed lead (E-type) results in a package case outline change from 98ASA10774D to 98ASA01044D.

Minimal impact associated with this lead frame change - no anticipated impact to board stencil / alignment, etc.

Previous case outline 98ASA10774D is attached to this notification, and can be found at:

<http://nxp.com/docs/en/package-information/98ASA10774D.pdf>

New case outline 98ASA01044D is attached to this notification, and can be found at:  
<http://nxp.com/docs/en/package-information/98ASA01044D.pdf>

Assembly site transfer was successfully qualified adhering to NXP specifications.  
Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-18

Please see the attached files for additional details.

**Why do we Implement this Change**

Qualification of ASECL, Taiwan and case outline change are required for manufacturing flexibility and customer supply assurance.

**Identification of Affected Products**

Product identification does not change

**Product Availability**

**Sample Information**

Samples are available from 14-Sep-2017  
Available sample part number: MC34671AEPR2

**Production**

Planned first shipment 01-Jan-2018

**Impact**

With the exception of minor case outline change, no other impact to form, fit, function or reliability.

**Data Sheet Revision**

A new datasheet will be issued

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 03-Oct-2017.

**Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Vivian Guo  
**Position** Product Engineer  
**e-mail address** Vivian.Guo@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MC34673AEPR2	935318976147	MC34673AEPR2	SINGLE CELL BATTERY CHG	HUSON8	RFS	BL Advanced Automotive Analog
MC34671AEPR2	935320968147	MC34671AEPR2	SINGLE CELL BATTERY CHG	HUSON8	RFS	BL Advanced Automotive Analog